

RRH040P03

Pch -30V -4A Power MOSFET

V _{DSS}	-30V
R _{DS(on)} (Max.)	75mΩ
I _D	±4A
P _D	2.0W

Features

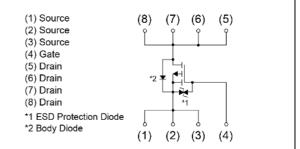
- 1) Low on-resistance
- 2) Small Surface Mount Package (SOP8)
- 3) Pb-free lead plating ; RoHS compliant
- 4) Halogen Free

Application

Switching

tline	(8)
3	(1) ₍₂₎ (7) ₍₆₎ (5)
3	

●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Basic ordering unit (pcs)	2500
	Taping code	ТВ
	Marking	RRH040P03

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V _{DSS}	-30	V	
Continuous drain current	I _D	±4	А	
Pulsed drain current	I _{DP} *1	±16	А	
Gate - Source voltage	V _{GSS}	±20	V	
Power dissipation	P _D ^{*2}	2.0	W	
Power dissipation	P _D *3	1.4	W	
Junction temperature	Tj	150	°C	
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C	

•Thermal resistance

Deremeter	Symbol	Values			Unit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance is notion empiont	R_{thJA}^{*2}	-	-	62.5	°C/W
Thermal resistance, junction - ambient	R_{thJA}^{*3}	-	-	89.2	°C/W

•Electrical characteristics (T_a = 25°C)

Deverseter	Current el	Canditiana	Values			Lincit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -1mA	-30	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	-24.1	-	mV/°C
Zero gate voltage drain current	I _{DSS}	V _{DS} = -30V, V _{GS} = 0V	-	-	-1	μA
Gate - Source leakage current	I _{GSS}	V_{GS} = ±20V, V_{DS} = 0V	-	-	±10	μA
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = -10V, I _D = -1mA	-1.0	-	-2.5	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	3.3	-	mV/°C
		V _{GS} = -10V, I _D = -4A	-	55	75	
Static drain - source on - state resistance	R _{DS(on)} *4	V _{GS} = -4.5V, I _D = -2A	-	85	115	mΩ
		V _{GS} = -4.0V, I _D = -2A	-	95	125	
Gate resistance	R _G	f = 1MHz, open drain	-	25	-	Ω
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = -10V, I _D = -4A	3	-	-	S

*1 Pw \leq 10µs, Duty cycle \leq 1%

- *2 Mounted on a ceramic board (30×30×0.8mm)
- *3 Mounted on a FR4 (25×25×0.8mm)
- *4 Pulsed



• Electrical characteristics ($T_a = 25^{\circ}C$)

Deremeter	Sympol	Conditions		Values		Lincit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	V _{GS} = 0V	-	480	-		
Output capacitance	C _{oss}	V _{DS} = -10V	-	70	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	70	-		
Turn - on delay time	$t_{d(on)}^{*4}$	$V_{DD} \simeq -15V, V_{GS} = -10V$	-	7	-		
Rise time	t _r *4	I _D = -2A	-	18	-	20	
Turn - off delay time	$t_{d(off)}^{*4}$	R _L ≃ 7.5Ω	-	50	-	ns	
Fall time	t _f *4	R _G = 10Ω	-	37	-		

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Deremeter	Symbol	Conditions	Values		Unit	
Parameter	Symbol Conditions	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Qg ^{*4}	V _{DD} ≃ -15V,	-	5.2	-	
Gate - Source charge	Q _{gs} *4	I _D = -4A,	-	1.6	-	nC
Gate - Drain charge	${\sf Q}_{\sf gd}{}^{*4}$	V _{GS} = -5V	-	1.6	-	

•Body diode electrical characteristics (Source-Drain) ($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ _S	$T = 25^{\circ}$	-	-	-1.6	А
Pulse forward current	I _{SP} *1	T _a = 25°C	-	-	-16	А
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = -4A	-	-	-1.2	V



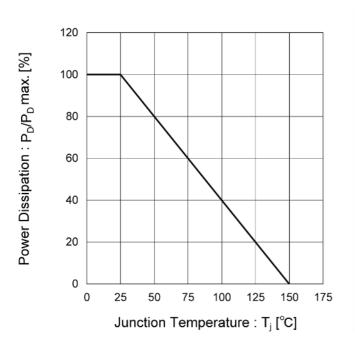


Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

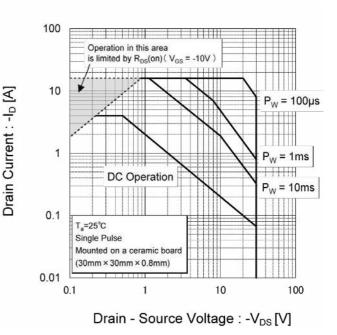
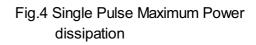
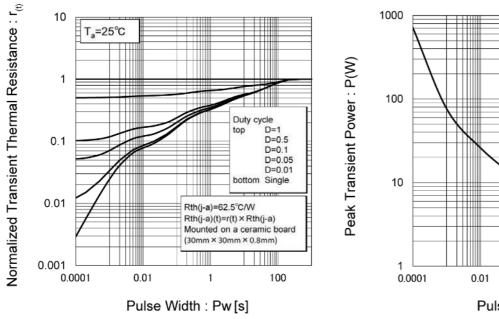
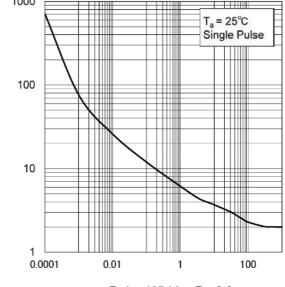


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width









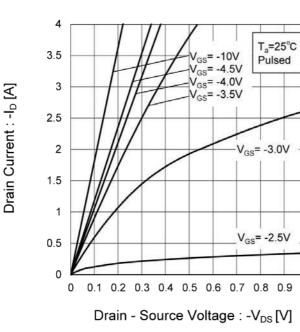
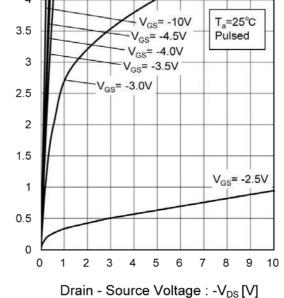


Fig.5 Typical Output Characteristics(I)

4 $V_{GS} = -10V$ $T_a = 25^{\circ}C$

Fig.6 Typical Output Characteristics(II)

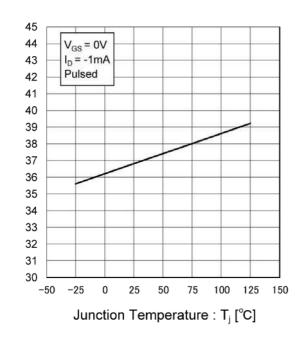


Drain Current : -I_D [A]

1

Fig.7 Breakdown Voltage vs. Junction Temperature

Drain-Source Breakdown Voltage : -V_{(BR)DSS} [V]





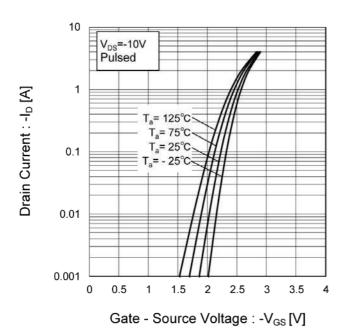


Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature

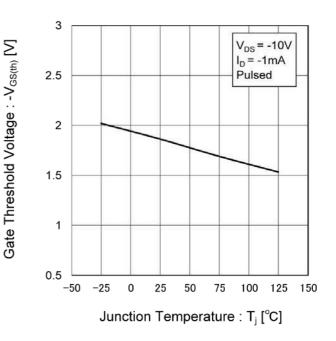
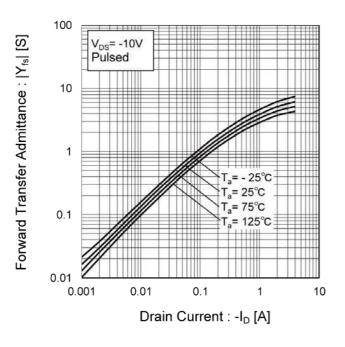


Fig.10 Forward Transfer Admittance vs. Drain Current





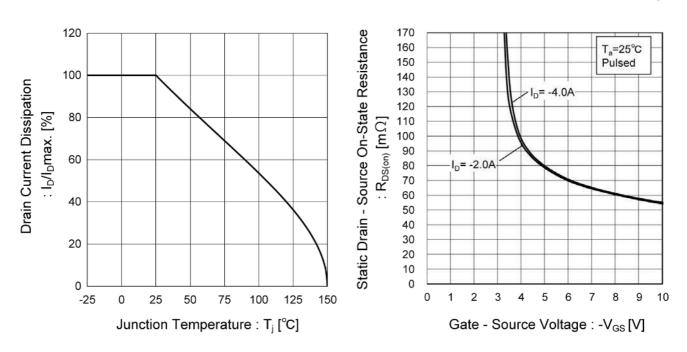
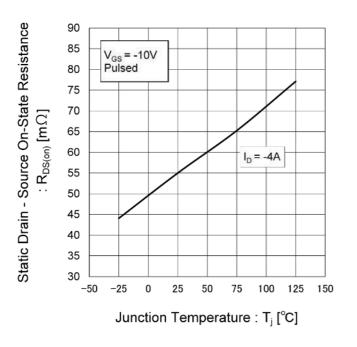


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature







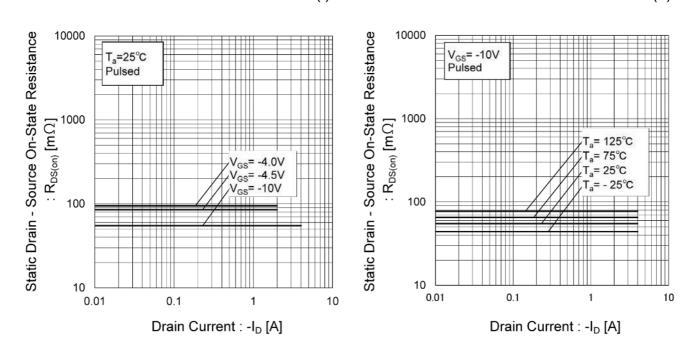


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

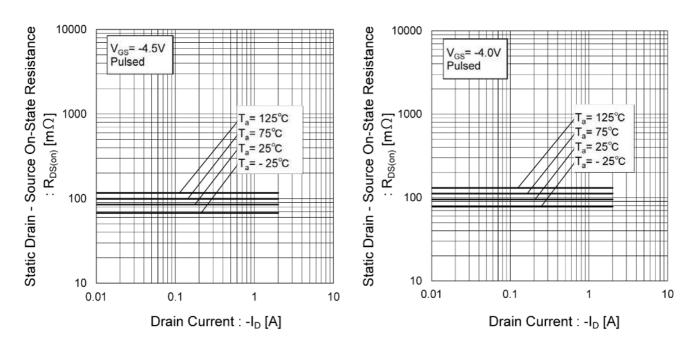
Fig.16 Static Drain - Source On - State

Resistance vs. Drain Current (III)

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current (IV)

Fig.15 Static Drain - Source On - State

Resistance vs. Drain Current (II)





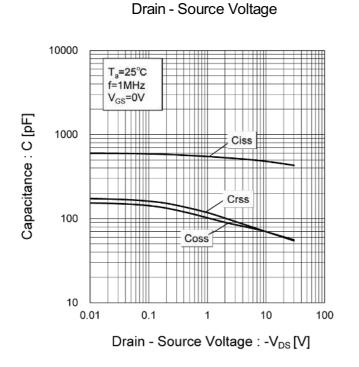


Fig.18 Typical Capacitance vs.

Fig.19 Switching Characteristics

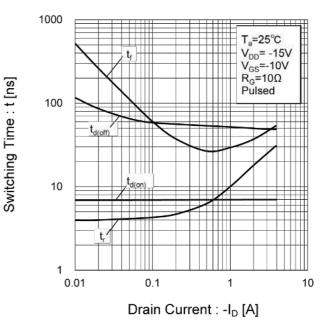


Fig.20 Dynamic Input Characteristics

Gate - Source Voltage : -V_{GS} [V]

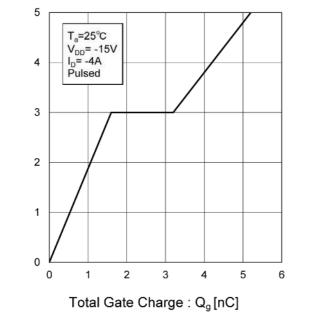
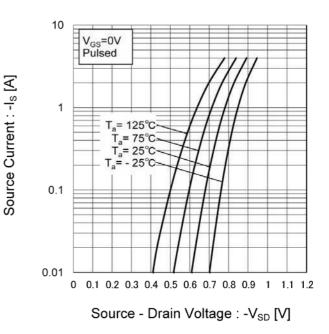


Fig.21 Source Current vs. Source Drain Voltage





• Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

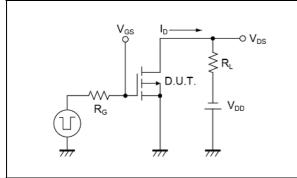


Fig.2-1 Gate Charge Measurement Circuit

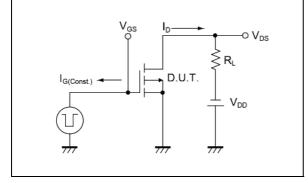
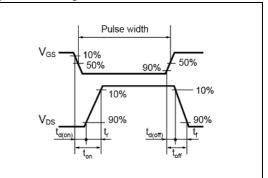
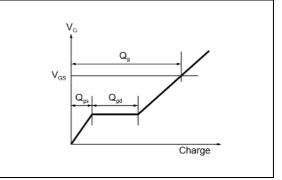


Fig.1-2 Switching Waveforms





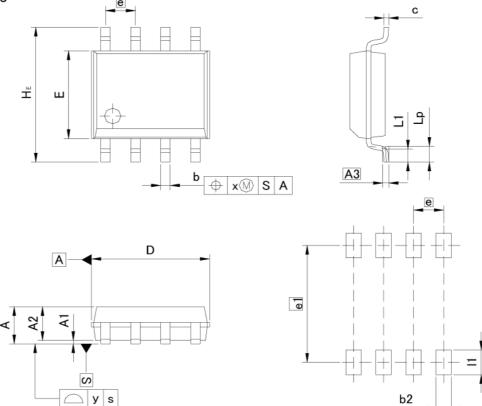


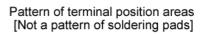


RRH040P03

Dimensions

SOP8





DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A	<u>-</u> 2	1.75		0.069
A1	0.	15	0.0	006
A2	1.40	1.60	0.055	0.063
A3	0.	25	0.0	10
b	0.30	0.50	0.012	0.020
С	0.10	0.30	0.004	0.012
D	4.80	5.20	0.189	0.205
E	3.75	4.05	0.148	0.159
е	1.	27	0.050	
HE	5.70	6.30	0.224	0.248
L1	0.40	0.60	0.016	0.024
Lp	0.65	0.85	0.026	0.033
x	0.15		0.0	06
У	0.10		0.0	104

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2		0.65		0.026
e1	5.15		0.1	203
11	T 2	1.15	ज्य ह	0.045

Dimension in mm/inches



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CLASSⅣ		CLASSⅢ	

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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